INTRODUCTION
Aeroflex Colorado Springs, a supplier of standard and semicustom integrated circuits, offers customized assembly and test capabilities targeted at customers needing low-volume or end-of-life assembly, COTS upscreening or QML process flows.

Aeroflex offers:
- One stop solution for your integrated assembly, evaluation, test and screening requirements
- Quick-turn capabilities available
- QML Q and QML V flows, MIL-PRF-38535 compliant, ISO-9001 certified
- Element evaluation
- Certified known good die program available
- Value-added services such as radiation testing, secure testing and COTS/commercial upscreening
- Class 100, 2600 sq. ft. Clean Room
- Analytical and DPA services

SPECIALIZED SERVICES
- Customer Furnished Tooling - Aeroflex has experience in assembling customer originated die, packages, test and screening requirements into a smooth, seamless high quality process.
- Radiation Testing - With over 20 years in the radiation-hardened IC arena, Aeroflex is experienced in the testing and characterization of ICs for space applications. Equipment includes:
  - JL Shepherd Irradiation System
  - Aracor X-Ray (wafer level irradiation)
- Secure Testing - Aeroflex has tested parts in a secure environment for classified programs for over 20 years. The facility and employees have the necessary clearances and the proper training.
- COTS/Commercial Upscreening - Aeroflex’s experience in the high-reliability marketplace allows us to perform additional testing and burn-in to your commercial parts to meet customized military requirements.
- Space Qualified Assembly Services - Aeroflex is a DLA certified QML V manufacturer of space qualified ICs.

PRODUCTION CAPABILITIES
Aeroflex can provide a complete solution for your integrated assembly, evaluation, test and screening requirements.

- Assembly
  - Wafer Backgrind
  - Wafer Saw
  - Assembly and Wirebond
    State-of-the art wirebonding; 60um pad pitch available
  - Commercial Flip Chip
  - COB (Chip-on-Board)
  - Standard or customizable Hermetic packages
    LCC, PGA, QFP, DIP, FP, Multi-chip modules
  - Solder Dip -- Meets MIL-STD-883, Method 2003
  - Mark
  - Internal Visual
    Meets MIL-STD-883, Method 2010, Cond A or B
- Burn-In Services
  - Static/Dynamic Burn-in
  - Accelerated Life Test
- Electrical Test
  - Wafer Level DC Parametrics
  - Memory, Logic and Analog IC Testing
  - Wafer Probe and Package IC Testing
  - High and Low Temperature IC Testing
  - LTX Trillium and Teradyne Testers
- Environmental Test
  - Hermeticity
    Meets MIL-STD-883, Method 1014, Cond A1, A2, C3
  - PIND
    Meets MIL-STD-883, Method 2020, Cond A, B
  - Centrifuge
  - Temp Cycle
    Meets MIL-STD-883, Method 1010, Cond A, B, C, D or F
  - Mechanical Shock and Variable Vibration
- Failure Analysis diagnostic capability down to the transistor level.
  - EDS, SEM, E-Beam, DPA
Aeroflex Colorado Springs - Datasheet Definition

Advanced Datasheet - Product In Development
Preliminary Datasheet - Shipping Prototype
Datasheet - Shipping QML & Reduced Hi-Rel

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Our passion for performance is defined by three attributes represented by these three icons: solution-minded, performance-driven and customer-focused.